

DWG. NO. SD-53309-**-27

E

D

C

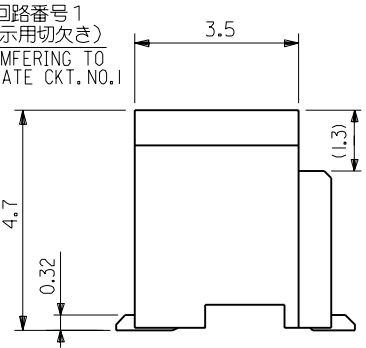
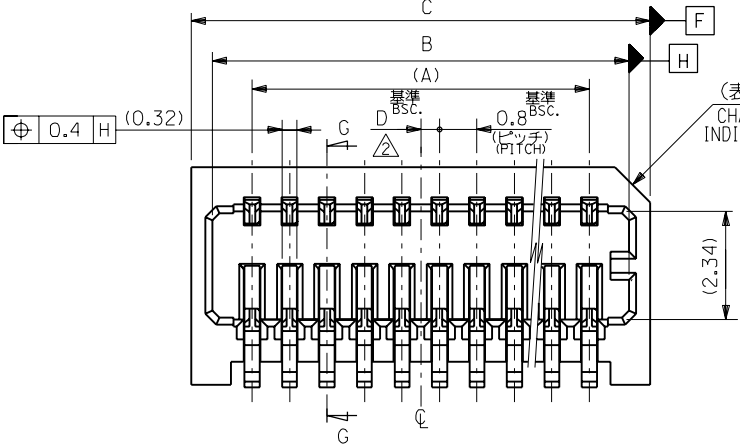
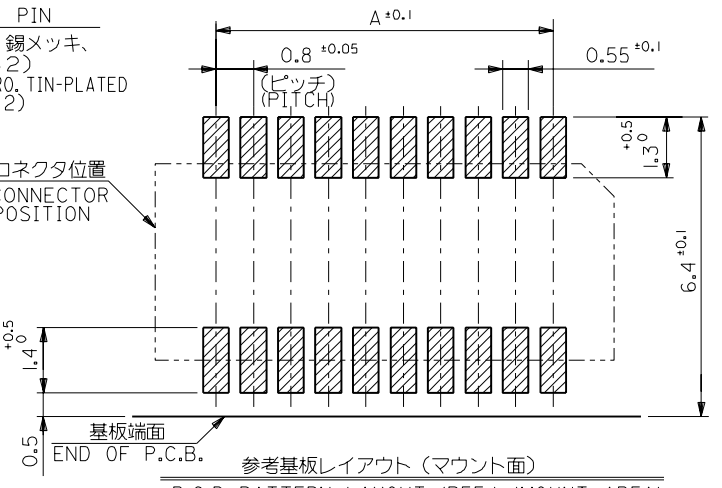
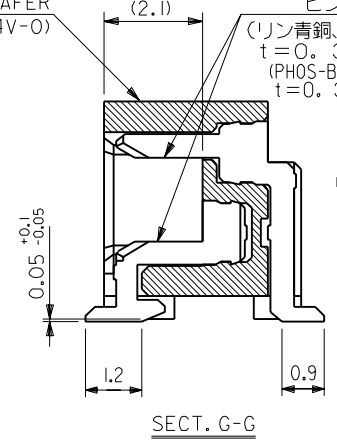
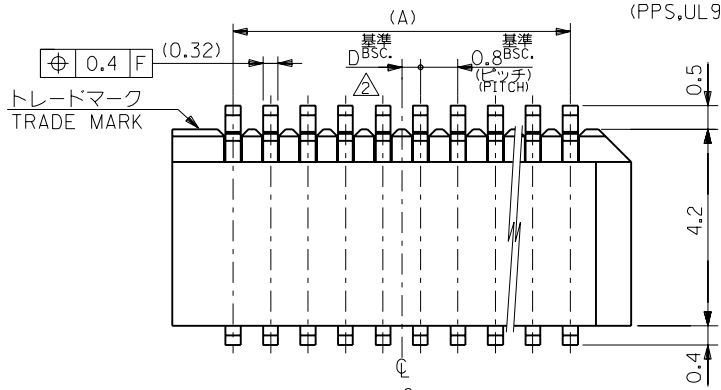
B

A

MM DIMENSIONS IN METRIC DO NOT SCALE DRAWING

ウェハ WAFER (PPS,UL94V-O)

ピン PIN (リン青銅、錫メッキ、 $t=0.32$) (PHOS-BRO. TIN-PLATED $t=0.32$)



参考基板レイアウト (マウント面)
P.C.B. PATTERN LAYOUT (REF.) (MOUNT AREA)

| | | | | | |
|-----|------|------|------|------------|---------|
| 0.4 | 17.8 | 16.9 | 15.2 | 53309-4027 | 40 |
| 0.8 | 17.0 | 16.1 | 14.4 | -3827 | 38 |
| 0.4 | 16.2 | 15.3 | 13.6 | -3627 | 36 |
| 0.8 | 15.4 | 14.5 | 12.8 | -3427 | 34 |
| 0.4 | 14.6 | 13.7 | 12.0 | -3227 | 32 |
| 0.8 | 13.8 | 12.9 | 11.2 | -3027 | 30 |
| 0.4 | 13.0 | 12.1 | 10.4 | -2827 | 28 |
| 0.8 | 12.2 | 11.3 | 9.6 | -2627 | 26 |
| 0.4 | 11.4 | 10.5 | 8.8 | -2427 | 24 |
| 0.8 | 10.6 | 9.7 | 8.0 | -2227 | 22 |
| 0.4 | 9.8 | 8.9 | 7.2 | -2027 | 20 |
| 0.8 | 9.0 | 8.1 | 6.4 | -1827 | 18 |
| 0.4 | 8.2 | 7.3 | 5.6 | -1627 | 16 |
| 0.8 | 7.4 | 6.5 | 4.8 | -1427 | 14 |
| 0.4 | 6.6 | 5.7 | 4.0 | -1227 | 12 |
| 0.8 | 5.8 | 4.9 | 3.2 | 53309-1027 | 10 |
| D | C | B | A | ENG. NO. | 極数 CKT. |

注記 NOTES

1. 炭合相手: 52465,52588 シリーズ
MATE WITH: 52465,52588 SERIES
- △ ウェハの C から隣接するピンの C 迄の位置を示す。
SHOW POSITION FROM C OF WAFER TO C OF ADJACENT PINS.

| 角度 ANGLE | 公差 TOLERANCES | 記号 LTR | 変更内容 REVISION RECORD | DR. CHK. | 日付 DATE |
|-----------------|---------------|--------|------------------------|----------|-----------|
| 30以上 OVER | +0.3 | B | 変更 REVISD (JC60094) | M.H. | '95/8/9 |
| 10以上 30未満 UNDER | +0.25 | A | 変更 REVISD (J30447) | T.S. | '93/5/1 |
| 10未満 UNDER | +0.2 | O | 新規作成 PROPOSED (J11001) | M.S. | '91/11/15 |

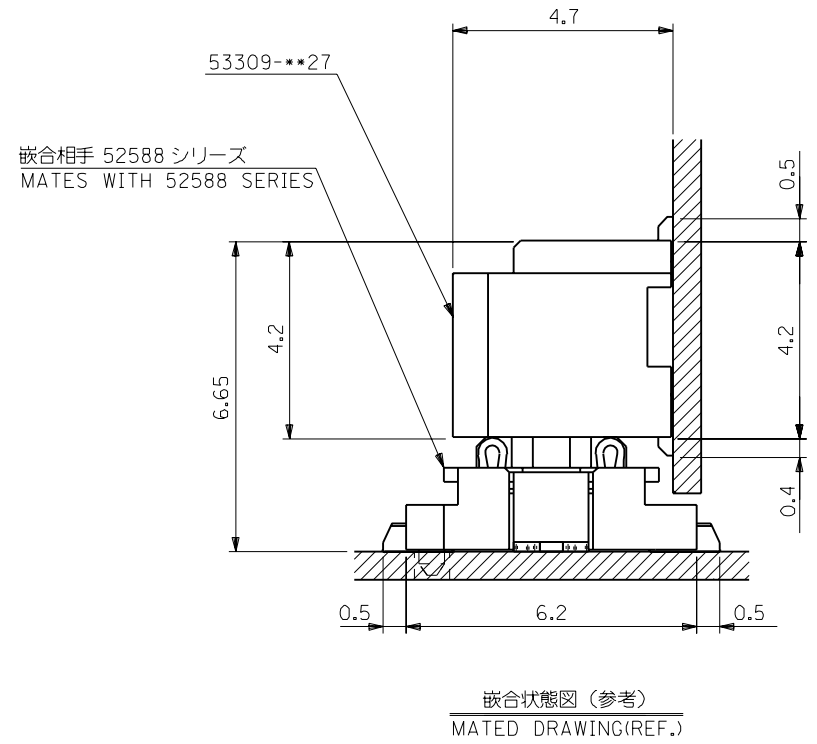
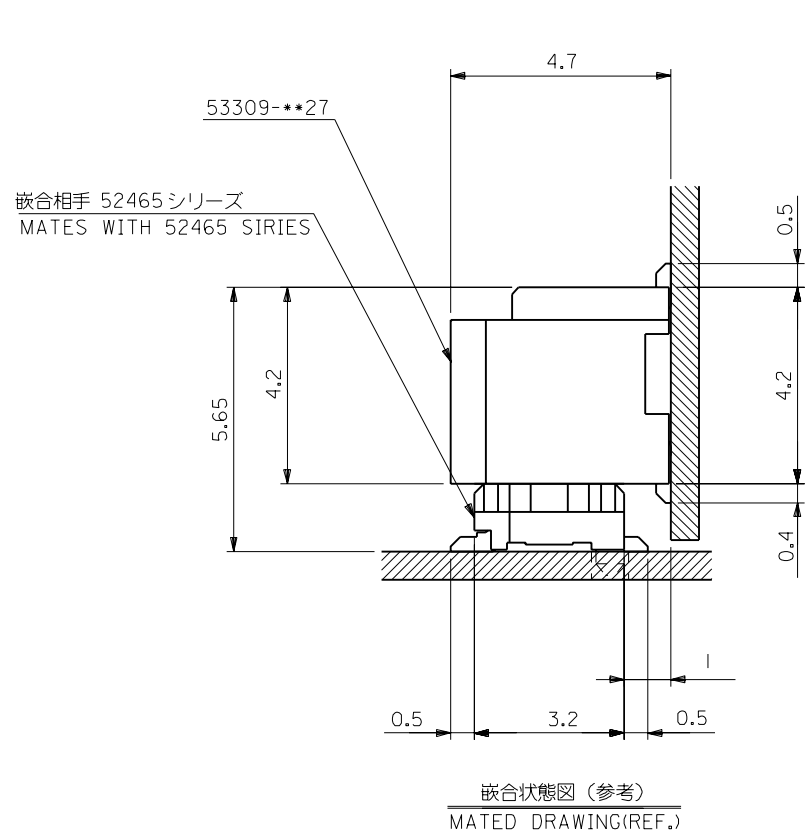
| | |
|--------------------|------------------|
| 材料 MATERIAL | ☑中参照 SEE DRAWING |
| 仕上げ FINISH | — |
| 適用電線範囲 WIRE RANGE | — |
| 被覆外径 INS. RANGE | — |
| DRAWN BY '91/11/14 | CHK'D BY '95/8/9 |
| K.ASAKAWA | Y.M.HIRAMOTO |
| APP'D BY '95/8/9 | 尺度 SCALE |
| M.FUKUSHIMA | — |

MOLEX-JAPAN CO.,LTD.
日本モレックス株式会社

REVISE ONLY ON CAD SYSTEM

TITLE 名称
0.8 BOARD TO BOARD CONN. WAFER ASS'Y R/A SMT (WITHOUT BOSS)

DWG. NO. (SHEET 1 OF 2) REV B
SD-53309-**-27



| 角度 ANGLE | 公差 | 記号 LTR | 変更内容 REVISION RECORD | DR. CHK. | 日付 DATE |
|-------------------------|-------|--------|----------------------|----------|-----------|
| 30°以上 OVER | +0.3 | B | 変更 (JC60094) | M.N.H. | '95/8/9 |
| 10°以上 30°未満 OVER UNDER | +0.25 | A | 変更 (J30447) | T.S. | '93/5/11 |
| 10°未満 UNDER | +0.2 | O | 新規作成 (J11001) | M.F. | '91/11/15 |
| 一般公差 GENERAL TOLERANCES | | | | | |

| | |
|--------------------|---------------------------------------|
| 材料 MATERIAL | SHEET 1 OF 2 参照 REFER TO SHEET 1 OF 2 |
| 仕上げ FINISH | — |
| 適用電線範囲 WIRE RANGE | — |
| 被覆外径 INS. RANGE | — |
| DRAWN BY '91/11/14 | CHK'D BY '95/8/9 |
| K.ASAKAWA | Y.M.HIRAMOTO |
| APP'D BY '95/8/9 | 尺度 SCALE |
| M.FUKUSHIMA | — |

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(WITHOUT BOSS)

DWG. NO. (SHEET 2 OF 2) REV
SD-53309-***27 B